



Material Content Data Sheet



Sales Product Name	TLE5012B E9000			Issued	22. January 2018			
MA#	MA001198366							
Package	PG-DSO-8-16			Weight*	83.53 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.535	4.23	4.23	42317	42317
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107	
	non noble metal	zinc	7440-66-6	0.036	0.04		429	
	non noble metal	iron	7439-89-6	0.717	0.86		8587	
wire	non noble metal	copper	7440-50-8	29.121	34.87	35.78	348653	357776
	noble metal	gold	7440-57-5	0.129	0.15	0.15	1539	1539
	encapsulation	organic material	carbon black	1333-86-4	0.094	0.11		1125
encapsulation	plastics	epoxy resin	-	4.321	5.17		51731	
	inorganic material	silicondioxide	60676-86-0	42.551	50.95	56.23	509441	562297
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9744	9744
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7785	7785
glue	plastics	acrylic resin	-	0.341	0.41		4079	
	noble metal	silver	7440-22-4	1.208	1.45	1.86	14463	18542
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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